

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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SERIAL NO.: 10/720,579 ART UNIT: 1753

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TITLE: METHOD FOR MANUFACTURING VERY LOW ROUGHNESS
ELECTRODEPOSITED COPPER FOIL AND ELECTRODEPOSITED COPPER FOIL
MANUFACTURED THEREBY

Amendment A: SPECIFICATION AMENDMENTS

On page 9, revise paragraph [0039] as follows:

In the following, the comparison example 1 that HEC is not added as an additive and the comparison example 2 that ~~Thiourea~~ thiourea is newly added without adding HEC and SPS will be described. The comparison examples are performed for comparing the material properties of the electrodeposited copper foil 400 which is manufactured when the additives according to the present invention are all added with those of the electrodeposited copper foil which is manufactured when a certain additive among the additives according to the present invention is not added.

On page 11, revise paragraph [0046] as follows:

As a conventional post-treatment of the electrodeposited copper foil 400, there are a nodule process adapted to further form a nodule on one side or both sides of the electrodeposited copper foil for increasing an adhesion with a resin, a barrier process adapted to prevent a copper from being diffused into a resin layer, a corrosion resisting process adapted to prevent an oxidation of a copper foil, and a silane coupling agent process adapted to enhance ~~a~~ an adhesion reliability when being adhered with a resin.